Special Issue

Advanced Artificial Intelligence Technologies and Applications in Manufacturing and Image Processing

Message from the Guest Editor

As artificial intelligence (AI) evolves, its integration with emerging technologies such as blockchain, edge computing, and the Internet of Things (IoT) is driving innovation across sectors including manufacturing, image processing, healthcare, smart cities, environmental monitoring, and industrial automation. This Special Issue mainly focuses on the latest advancements in AI technologies and their transformative applications in the field of manufacturing and image processing. We aim to gather cutting-edge research on topics such as advanced AI algorithms, scalable machine learning models, AI-driven decision-making systems, and secure, decentralized architectures. We invite contributions that explore novel methodologies, practical implementations, and interdisciplinary approaches to addressing real-world challenges using next-generation AI technologies in manufacturing and image processing.

Guest Editor

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As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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